

| L Number | Hits | Search Text  | DB                              | Time stamp       |
|----------|------|--|---------------------------------|------------------|
| 8        | 593  | ('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)   | USPAT;<br>US-PGPUB;<br>EPO; JPO | 2003/09/09 07:45 |
| 9        | 587  | ((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3  | USPAT;<br>US-PGPUB;<br>EPO; JPO | 2003/09/09 07:40 |
| 10       | 587  | ((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water   | USPAT;<br>US-PGPUB;<br>EPO; JPO | 2003/09/09 07:41 |
| 11       | 208  | ((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3   | USPAT;<br>US-PGPUB;<br>EPO; JPO | 2003/09/09 07:41 |
| 12       | 207  | ((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3) and (wafer substrate workpiece)  | USPAT;<br>US-PGPUB;<br>EPO; JPO | 2003/09/09 07:42 |
| 13       | 128  | ((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3) and (wafer substrate workpiece)) and polishing adj slurry  | USPAT;<br>US-PGPUB;<br>EPO; JPO | 2003/09/09 07:58 |
| 14       | 54   | ((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3) and (wafer substrate workpiece)) and polishing adj slurry) and (slurry with dispersion)  | USPAT;<br>US-PGPUB;<br>EPO; JPO | 2003/09/09 07:42 |
| 15       | 53   | ((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3) and (wafer substrate workpiece)) and polishing adj slurry) and (slurry with dispersion)) and ( "CMP" "(CMP)")  | USPAT;<br>US-PGPUB;<br>EPO; JPO | 2003/09/09 07:45 |
| 19       | 62   | ((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3) and (wafer substrate workpiece)) and (polishing adj slurry with silica)  | USPAT;<br>US-PGPUB;<br>EPO; JPO | 2003/09/09 07:59 |
| 20       | 38   | ((('CMP' '(CMP)' chemical adj mechanical adj polishing) with (slurry with water)) and polish\$3) and water) and dilut\$3) and (wafer substrate workpiece)) and polishing adj slurry) and (slurry with dispersion)) and ( "CMP" "(CMP)") and (polishing adj slurry with silica) | USPAT;<br>US-PGPUB;<br>EPO; JPO | 2003/09/09 07:59 |
| 21       | 1    |  | USPAT                           | 2003/09/09 08:03 |